



Two-wire Serial EEPROM

BM24C04D

Bestow Mascot

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1. Description

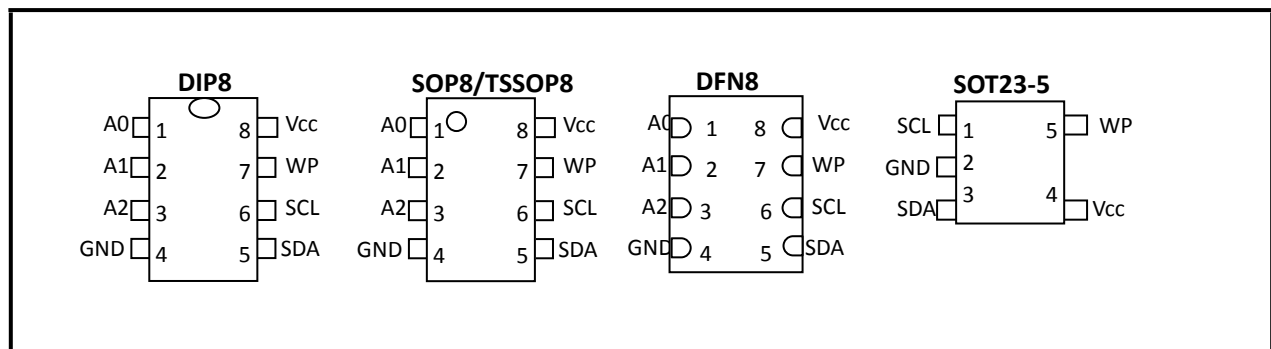
1.1 General Description

The BM24C04D provides 4,096 bits of serial electrically erasable and programmable read-only memory (EEPROM) organized as 512 words of 8 bits each. The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential. The BM24C04D is available in space-saving DIP8/SOP8/TSSOP8/ SOT23-5 and DFN8 Packages and is accessed via a two-wire serial interface.

1.2 Features

- Low-voltage and Standard-voltage Operation
 - 1.7 ($V_{CC} = 1.7V$ to $5.5V$)
 - Operating Ambient Temperature: $-40^{\circ}C$ to $+85^{\circ}C$
 - Internally Organized: - 512 X 8 bits
 - Two-wire Serial Interface
 - Schmitt Trigger, Filtered Inputs for Noise Suppression
 - Bidirectional Data Transfer Protocol
 - 1 MHz (5V), 400 kHz (1.7V, 2.5V, 2.7V)
- Compatibility
- Write Protect Pin for Hardware Data Protection
 - 16-byte Page Write Modes
 - Partial Page Writes Allowed
 - Self-timed Write Cycle (5 ms max)
 - High-reliability
 - Endurance: 1 Million Write Cycles
 - Data Retention: 100 Years
 - DIP8/SOP8/TSSOP8/ SOT23-5 and DFN8 Packages

1.3 Pin Configuration



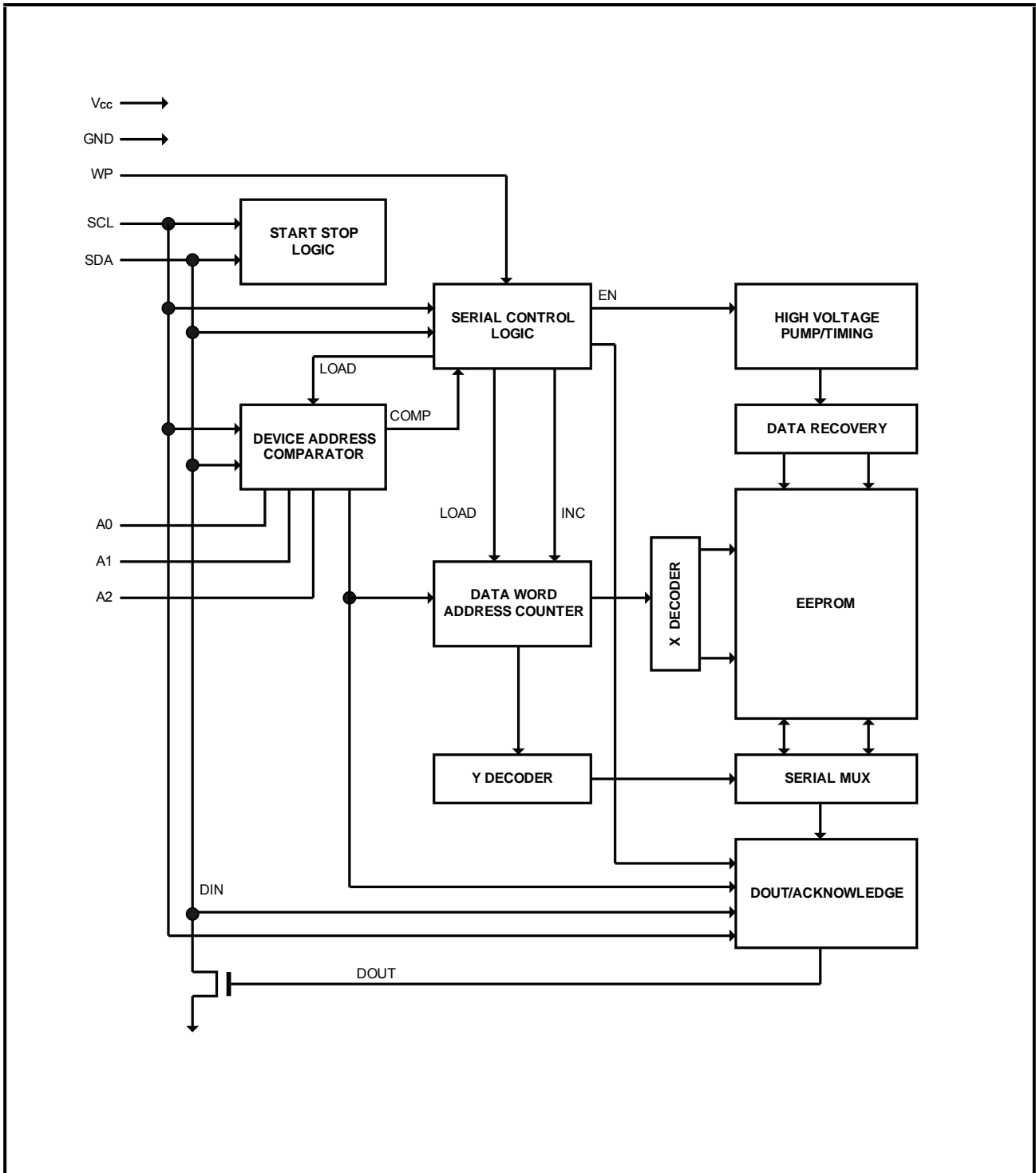
2. Pin Descriptions

Pin number	Designation	Name and Functions
1 – 3	A0 - A2	DEVICE/PAGE ADDRESSES (A2, A1, A0): The BM24C04 uses the A2 and A1 inputs for hard wire addressing and a total of four 4K devices may be addressed on a single bus system. The A0 pin is a no connect and can be connected to ground.
5	SDA	SERIAL DATA (SDA): The SDA pin is bi-directional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open-collector devices.
6	SCL	SERIAL CLOCK (SCL): The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.
7	WP	WRITE PROTECT (WP): The BM24C04D has a Write Protect pin that provides hardware data protection. The Write Protect pin allows normal read/write operations when connected to ground (GND). When the Write Protect pin is connected to V _{CC} , the write protection feature is enabled and operates as shown in the following Table 1.
4	GND	Ground
8	V _{CC}	Power Supply

Table 1 Write Protect

WP Pin Status:	Part of the Array Protected
At V _{CC}	Full (4K) Array
At GND	Normal Read/Write Operations

3. Block Diagram



4. Functional Description

4.1 Memory Organization

BM24C04D, 4K SERIAL EEPROM: Internally organized with 32 pages of 16 bytes each, the 4K requires an 9-bit data word address for random word addressing.

4.2 Device Operation

CLOCK and DATA TRANSITIONS: The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods (see to Figure 1 on page 4). Data changes during SCL high periods will indicate a start or stop condition as defined below.

START CONDITION: A high-to-low transition of SDA with SCL high is a start condition which must precede any other command (see to Figure 2 on page 5).

STOP CONDITION: A low-to-high transition of SDA with SCL high is a stop condition. After a read sequence, the stop command will place the EEPROM in a standby power mode (see Figure 2 on page 5).

ACKNOWLEDGE: All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a “0” to acknowledge that it has received each word. This happens during the ninth clock cycle.

STANDBY MODE: The BM24C04D features a low-power standby mode which is enabled: (a) upon power-up and (b) after the receipt of the STOP bit and the completion of any internal operations.

MEMORY RESET: After an interruption in protocol, power loss or system reset, any two-wire part can be reset by following these steps:

- Clock up to 9 cycles.
- Look for SDA high in each cycle while SCL is high.
- Create a start condition.

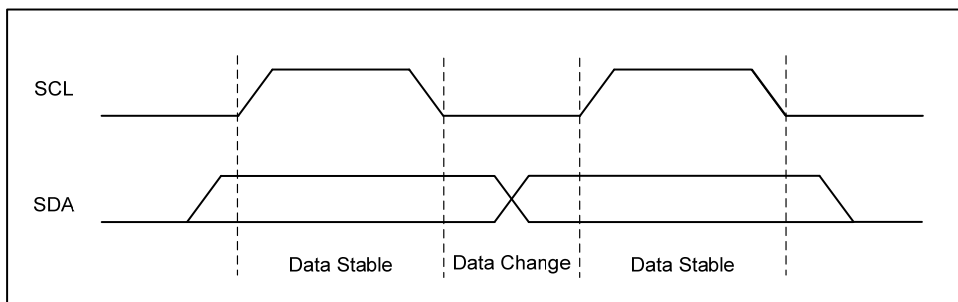


Figure1. Data Validity

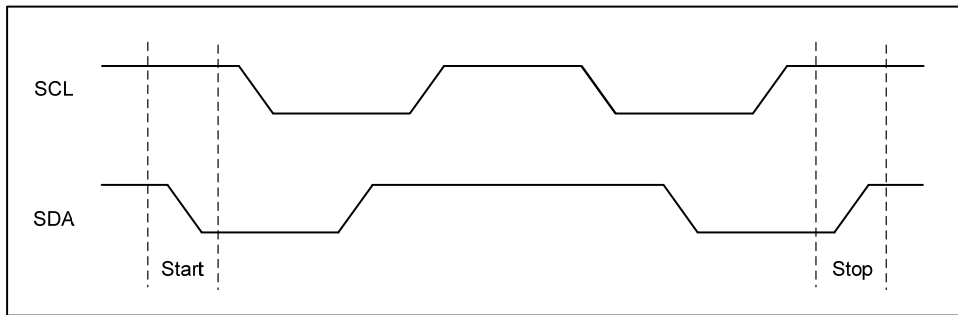


Figure 2. Start and Stop Definition

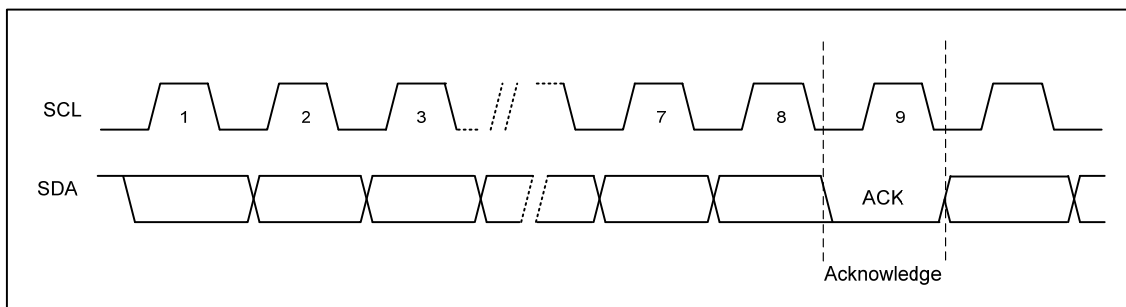


Figure 3. Output Acknowledge

4.3 Device Addressing

The BM24C04D EEPROM devices require an 8-bit device address word following a start condition to enable the chip for a read or write operation (see to Figure 4 on page 7).

The device address word consists of a mandatory "1", "0" sequence for the first four most significant bits as shown. This is common to all the Serial EEPROM devices.

The BM24C04D EEPROM only uses the A2 and A1 device address bits with the third bit being a memory page address bit. The two device address bits must compare to their corresponding hardwired input pins. The A0 pin is no connect.

The eighth bit of the device address is the read/write operation select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

Upon a compare of the device address, the EEPROM will output a "0". If a compare is not made, the chip will return to a standby state.

4.4 Write Operations

BYTE WRITE: A write operation requires an 8-bit data word address following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a "0" and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a "0" and the addressing device, such as a microcontroller, must terminate the write sequence with a stop condition. At this time the EEPROM enters an internally timed write cycle, t_{WR} , to the nonvolatile memory. All inputs

are disabled during this write cycle and the EEPROM will not respond until the write is complete (see Figure 5 on page 7).

PAGE WRITE: The 4K EEPROM is capable of a 16-byte page write.

A page write is initiated the same as a byte write, but the microcontroller does not send a stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to fifteen more data words. The EEPROM will respond with a "0" after each data word received. The microcontroller must terminate the page write sequence with a stop condition (see Figure 6 on page 7).

The data word address lower four bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than sixteen data words are transmitted to the EEPROM, the data word address will "roll over" and previous data will be overwritten.

ACKNOWLEDGE POLLING: Once the internally timed write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a start condition followed by the device address word. The read/write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a "0", allowing the read or write sequence to continue.

4.5 Read Operations

Read operations are initiated the same way as write operations with the exception that the read/write select bit in the device address word is set to "1". There are three read operations: current address read, random address read and sequential read.

CURRENT ADDRESS READ: The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address "roll over" during read is from the last byte of the last memory page to the first byte of the first page. The address "roll over" during write is from the last byte of the current page to the first byte of the same page.

Once the device address with the read/write select bit set to "1" is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input "0" but does generate a following stop condition (see Figure 7 on page 8).

RANDOM READ: A random read requires a "dummy" byte write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a current

address read by sending a device address with the read/write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a “0” but does generate a following stop condition (see Figure 8 on page 8).

SEQUENTIAL READ: Sequential reads are initiated by either a current address read or a random address read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address limit is reached, the data word address will “roll over” and the sequential read will continue. The sequential read operation is terminated when the microcontroller does not respond with a “0” but does generate a following stop condition (see Figure 9 on page 8)

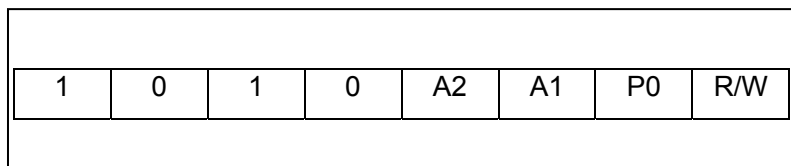


Figure 4 Device Address

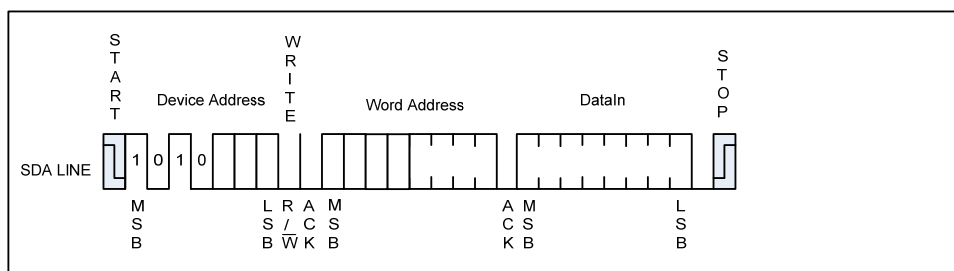


Figure 5 Byte Write

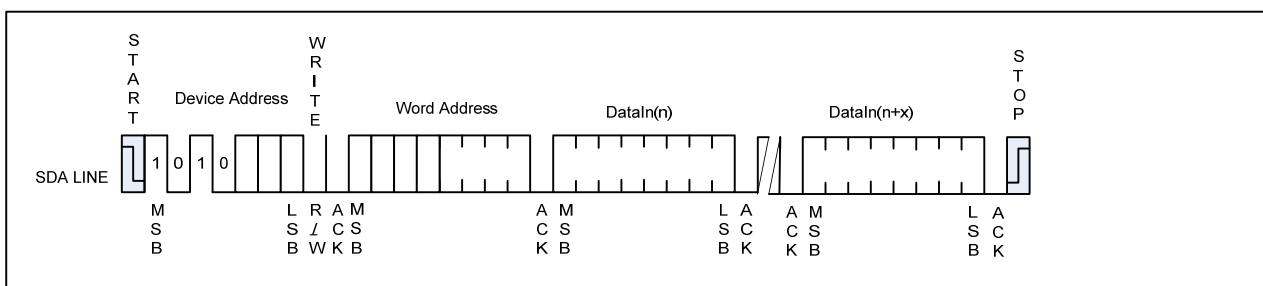


Figure 6. Page Write

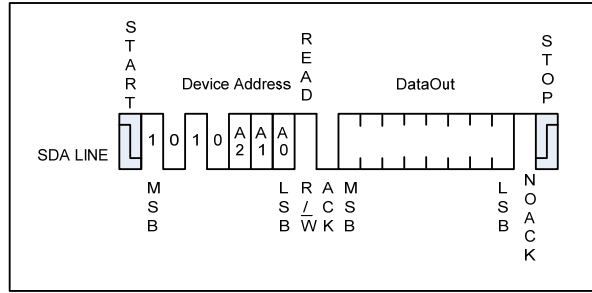


Figure 7 Current Address Read

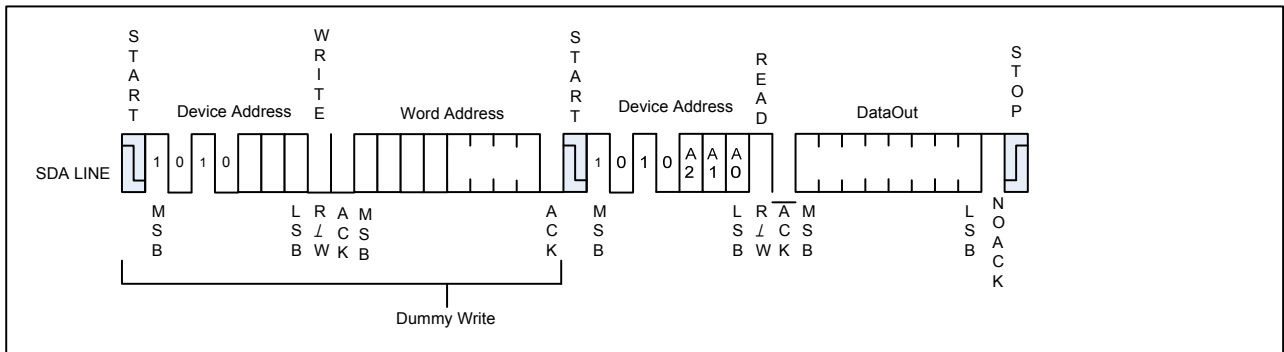


Figure 8 Random Read

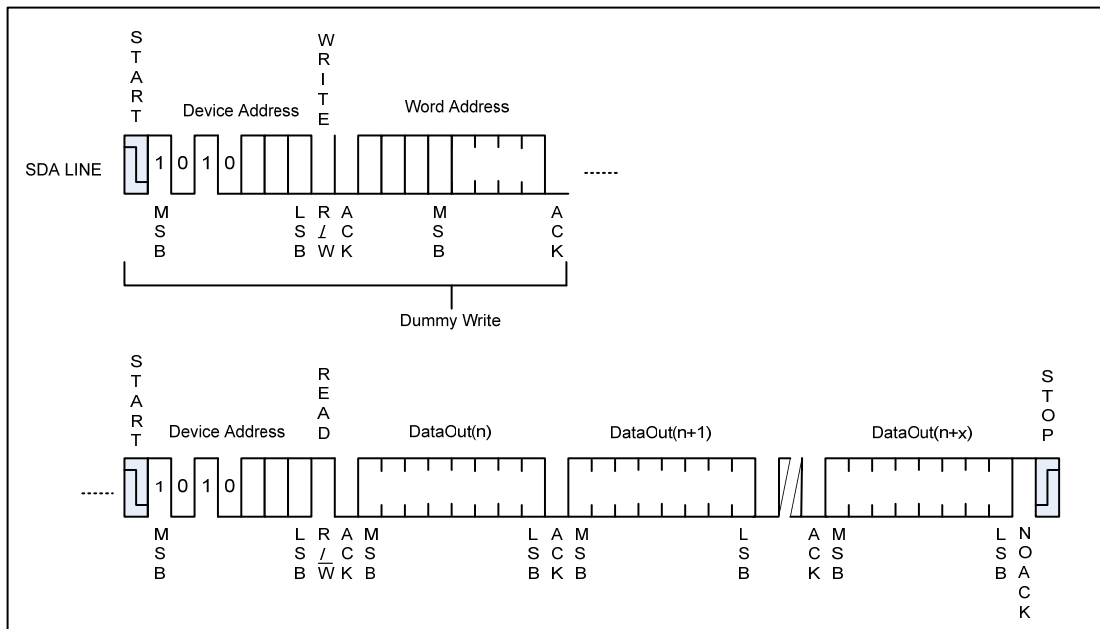


Figure 9. Sequential Read

5. Electrical Characteristics

5.1 Absolute Maximum Stress Ratings

DC Supply Voltage.....-0.3V to +6.5V

Input/ Output Voltage..... GND-0.3V to $V_{CC}+0.3V$

Operating Ambient Temperature ...-40°C to +85°C

Storage Temperature.....-65°C to +150°C

Comments: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to this device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

5.2 DC Electrical Characteristics

Applicable over recommended operating range from: $T_A=-40^{\circ}C$ to $+85^{\circ}C$, $V_{CC}=+1.7V$ to $+5.5V$ (unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Supply Voltage	V_{CC}	1.7	-	5.5	V	
Supply Current $V_{CC} = 5.0V$	I_{CC1}	-	0.4	1.0	mA	READ at 100 kHz
Supply Current $V_{CC} = 5.0V$	I_{CC2}	-	2.0	3.0	mA	WRITE at 100 kHz
Standby Current $V_{CC} = 5.0V$	I_{SB}	-	-	1.0	μA	$V_{IN}= V_{CC}$ or GND
Input Leakage Current	I_{LI}	-	-	3.0	μA	$V_{IN}=V_{CC}$ or GND
Output Leakage Current	I_{LO}	-	0.05	3.0	μA	$V_{OUT}=V_{CC}$ or GND
Input Low Level	V_{IL1}	-0.3	-	$V_{CC} \times 0.3$	V	$V_{CC}=1.7V$ to $5.5V$
Input High Level	V_{IH1}	$V_{CC} \times 0.7$	-	$V_{CC} + 0.3$	V	$V_{CC}=1.7V$ to $5.5V$
Input Low Level	V_{IL2}	-0.3	-	$V_{CC} \times 0.2$	V	$V_{CC}=1.7V$
Input High Level	V_{IH2}	$V_{CC} \times 0.7$	-	$V_{CC} + 0.3$	V	$V_{CC}=1.7V$
Output Low Level $V_{CC} =5.0V$	V_{OL3}	-	-	0.4	V	$I_{OL}=3.0mA$
Output Low Level $V_{CC} =3.0V$	V_{OL2}	-	-	0.4	V	$I_{OL}=2.1 mA$
Output Low Level $V_{CC} =1.7V$	V_{OL1}	-	-	0.2	V	$I_{OL}=0.15 mA$

5.3 Pin Capacitance

Applicable over recommended operating range from $T_A = 25^{\circ}C$, $f = 1.0 MHz$, $V_{CC} = +1.7V$

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Input/output Capacitance (SDA)	C_{IO}	-	-	8	pF	$V_{IO}= 0V$
Input Capacitance (A0, A1, A2, SCL)	C_{IN}	-	-	6	pF	$V_{IN}= 0V$

5.4 AC Electrical Characteristics

Applicable over recommended operating range from $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = +1.7\text{V}$ to $+5.5\text{V}$, $C_L = 1$ TTL Gate and 100 pF (unless otherwise noted)

Parameter	Symbol	1.7V ≤ V _{CC} < 2.5V			2.5V ≤ V _{CC} ≤ 5.5V			Units
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Clock Frequency, SCL	f _{SCL}	-	-	400	-	-	1000	kHz
Clock Pulse Width Low	t _{LOW}	1.2	-	-	0.7	-	-	μs
Clock Pulse Width High	t _{HIGH}	0.4	-	-	0.3	-	-	μs
Noise Suppression Time	t _I	-	-	100	-	-	50	ns
Clock Low to Data Out Valid	t _{AA}	0.3	-	0.9	0.2	-	0.7	μs
Time the bus must be free before a new transmission can start	t _{BUF}	1.2	-	-	0.5	-	-	μs
Start Hold Time	t _{HD.STA}	0.6	-	-	0.25	-	-	μs
Start Setup Time	t _{SU.STA}	0.6	-	-	0.25	-	-	μs
Data In Hold Time	t _{HD.DAT}	0	-	-	0	-	-	μs
Data In Setup Time	t _{SU.DAT}	100	-	-	100	-	-	ns
Inputs Rise Time	t _R	-	-	0.3	-	-	0.3	μs
Inputs Fall Time	t _F	-	-	300	-	-	100	ns
Stop Setup Time	t _{SU.STO}	0.6	-	-	0.25	-	-	μs
Data Out Hold Time	t _{DH}	50	-	-	50	-	-	ns
Write Cycle Time	t _{WR}	-	3	5	-	3	5	ms
5.0V, 25°C, Byte Mode	Endurance	1M	-	-	-	-	-	Write Cycles

Note:

1. This parameter is characterized and is not 100% tested.
2. AC measurement conditions: R_L (connects to V_{CC}): $1.3\text{k}\Omega$ (2.5V, 5V), $10\text{k}\Omega$ (1.7V)
 Input pulse voltages: $0.3 V_{CC}$ to $0.7 V_{CC}$
 Input rise and fall time: $\leq 50\text{ ns}$
 Input and output timing reference voltages: $0.5 V_{CC}$
 The value of R_L should be concerned according to the actual loading on the user's system.

Bus Timing:

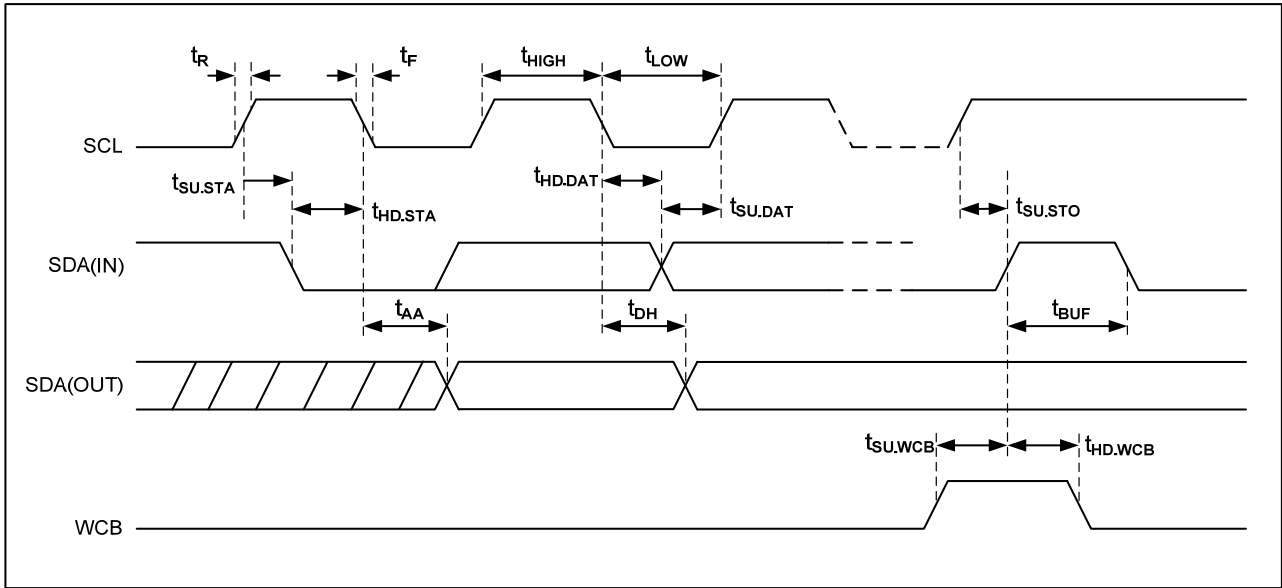
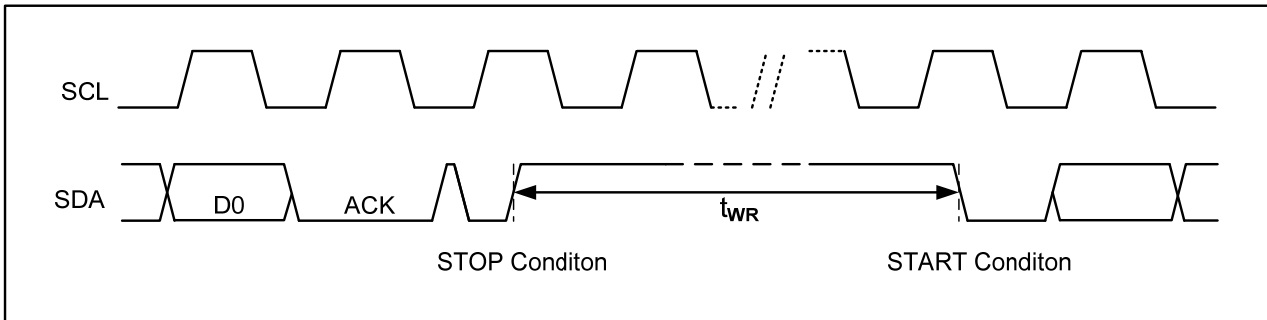


Figure10 SCL: Serial Clock, SDA: Serial Data I/O

Write Cycle Timing:

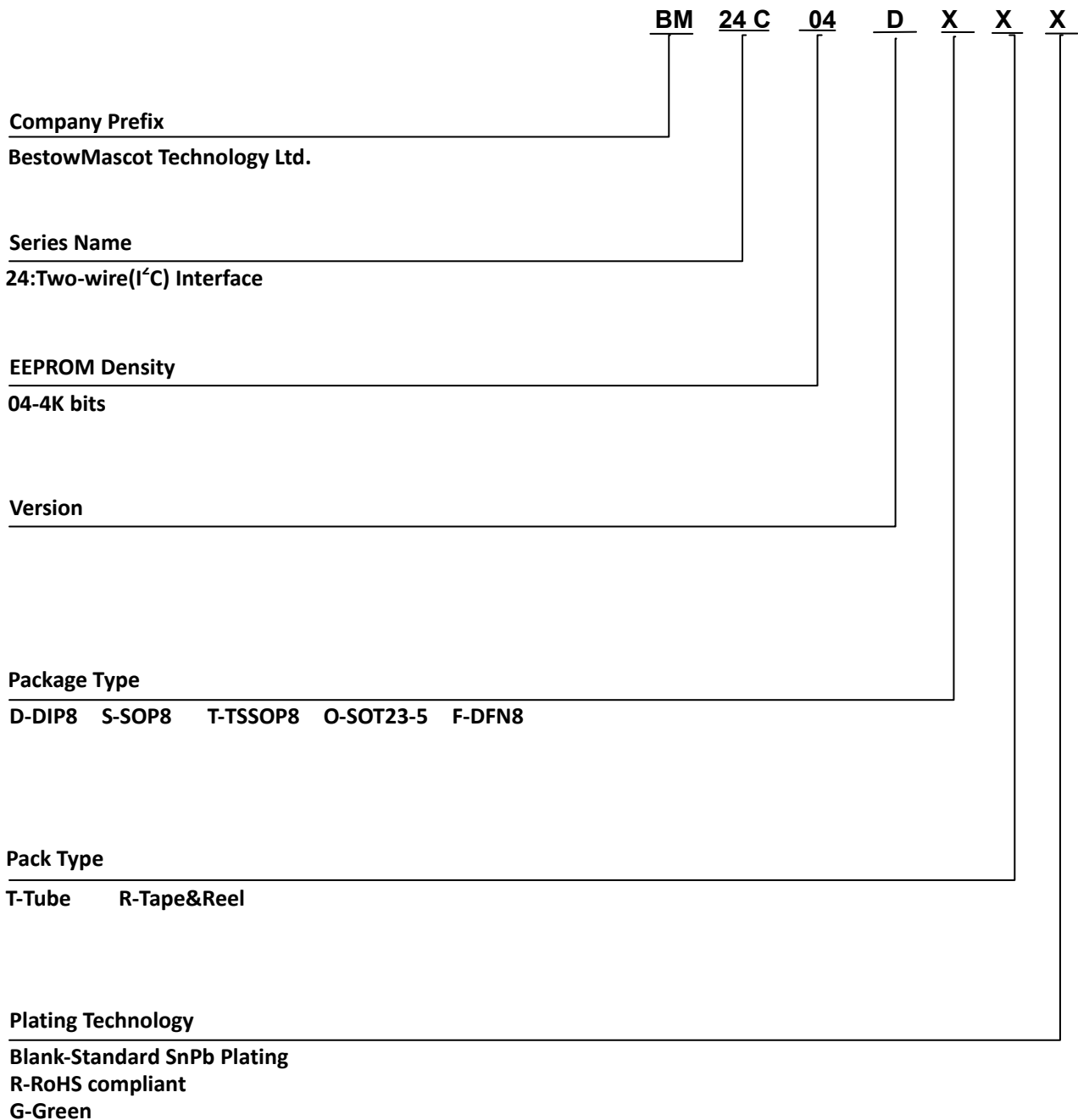


Note: The write cycle time t_{WR} is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle.

Figure 11 SCL: Serial Clock, SDA: Serial Data I/O

6. Ordering Information

6.1 Naming Scheme



Model	DIP8	SOP8	TSSOP8	SOT23-5	DFN8
BM24C04D	√	√	√	√	√

√: Mass-produced

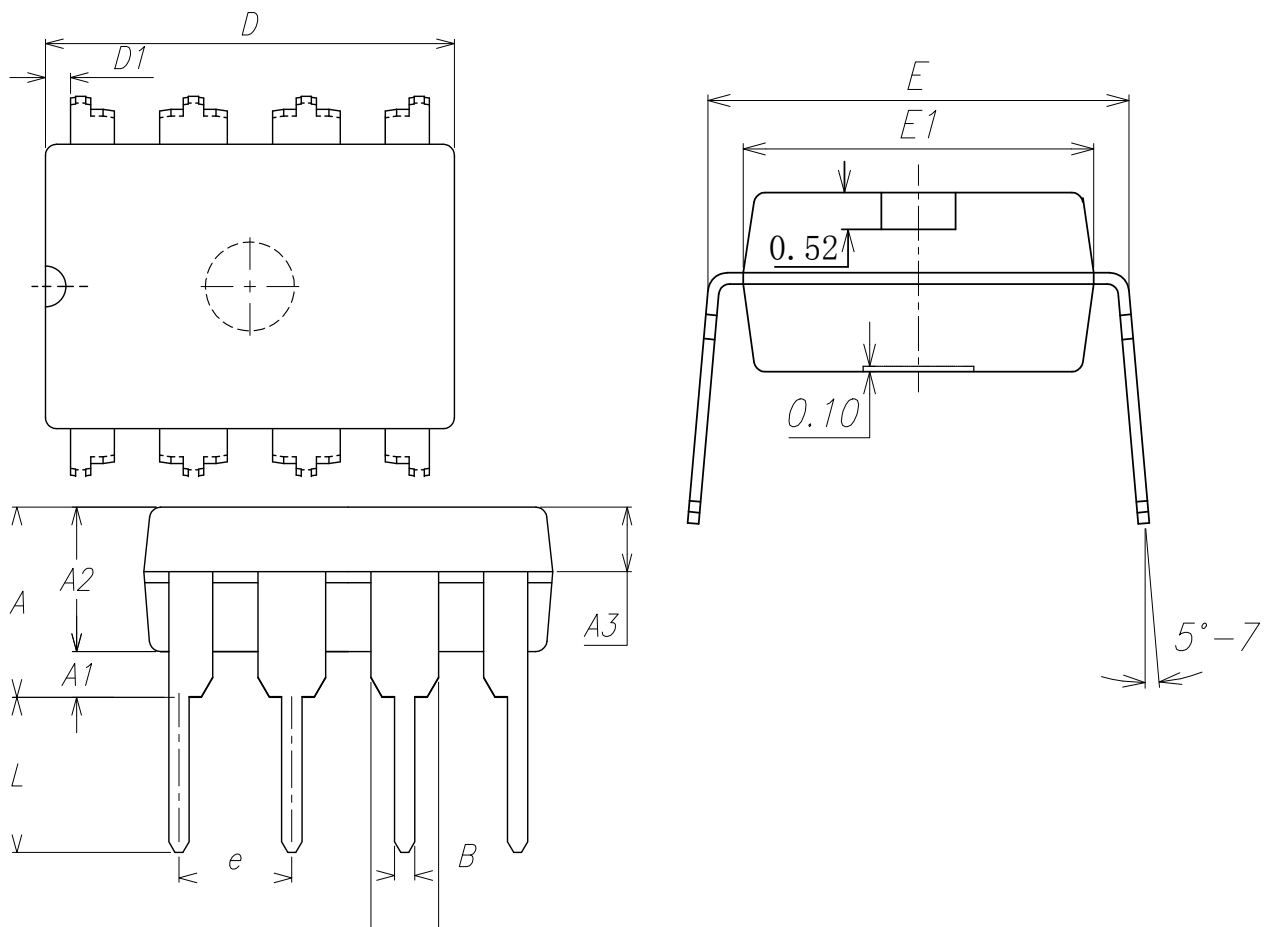
* : Design in

-: Be customized

6.2 Order Information

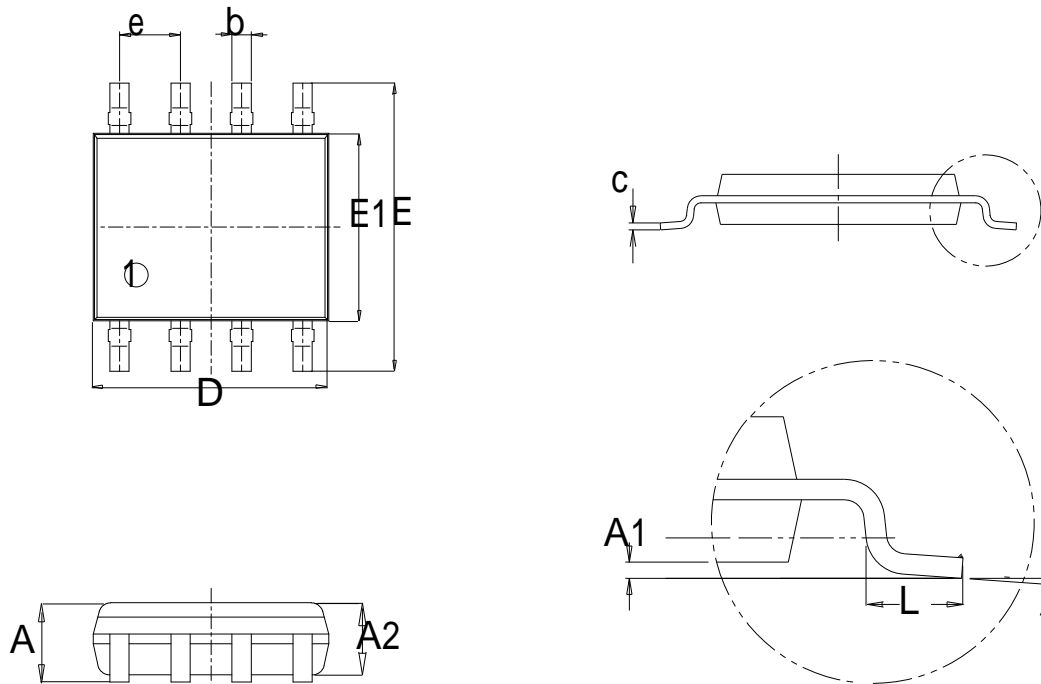
Package	Temperature Range	Vcc	HSF	Packaging	Order Code
DIP8	-40°C-85°C	1.7V-5.5V	RoHS	Tube	BM24C04D-D-T-R
			Green	Tube	BM24C04D-D-T-G
SOP8	-40°C-85°C	1.7V-5.5V	RoHS	Tube	BM24C04D-S-T-R
				Tape and Reel	BM24C04D-S-R-R
			Green	Tube	BM24C04D-S-T-G
				Tape and Reel	BM24C04D-S-R-G
TSSOP8	-40°C-85°C	1.7V-5.5V	RoHS	Tube	BM24C04D-T-T-R
				Tape and Reel	BM24C04D-T-R-R
			Green	Tube	BM24C04D-T-T-G
				Tape and Reel	BM24C04D-T-R-G
SOT23-5	-40°C-85°C	1.7V-5.5V	RoHS	Tape and Reel	BM24C04D-O-R-R
			Green	Tape and Reel	BM24C04D-O-R-G
DFN8	-40°C-85°C	1.7V-5.5V	RoHS	Tape and Reel	BM24C04D-F-R-R
			Green	Tape and Reel	BM24C04D-F-R-G

6.3 DIP8 Package Outline Dimensions



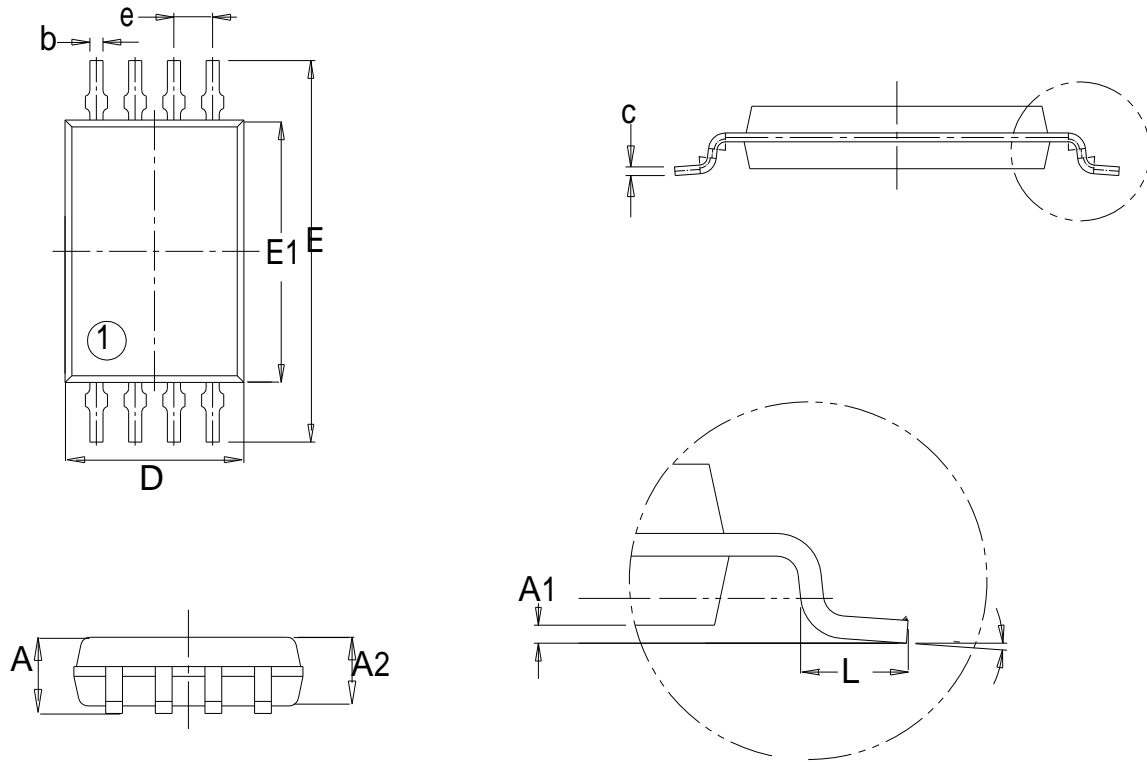
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	3.60	4.00	0.142	0.157
A1	0.51	-	0.020	-
A2	3.10	3.50	0.122	0.138
A3	1.50	1.70	0.059	0.067
B	0.44	0.53	0.017	0.021
B1	1.52	1.57	0.060	0.062
D	9.20	9.25	0.362	0.364
D1	0.561	0.611	0.022	0.024
E	7.63	7.68	0.300	0.302
E1	6.35	6.40	0.250	0.252
e	2.54BSC		0.100 BSC	
L	3.49	3.81	0.138	0.150

6.4 SOP8 Package Outline Dimensions



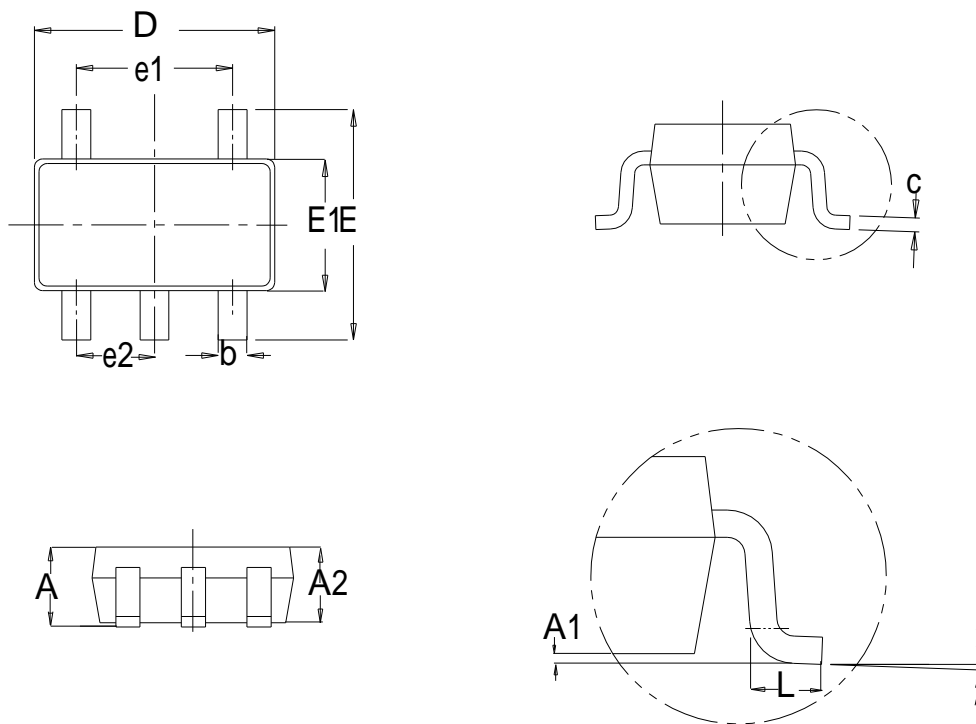
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.650	0.053	0.065
A1	0.100	0.250	0.004	0.010
A2	1.450	1.525	0.057	0.060
b	0.375	0.425	0.015	0.017
c	0.245 (BSC)		0.010 (BSC)	
D	4.875	4.925	0.192	0.194
E	5.900	6.100	0.232	0.240
E1	3.825	3.925	0.151	0.155
e	1.245	1.295	0.049	0.051
L	0.615	0.765	0.024	0.030
α	0°	5°	0°	5°

6.5 TSSOP8 Package Outline Dimensions



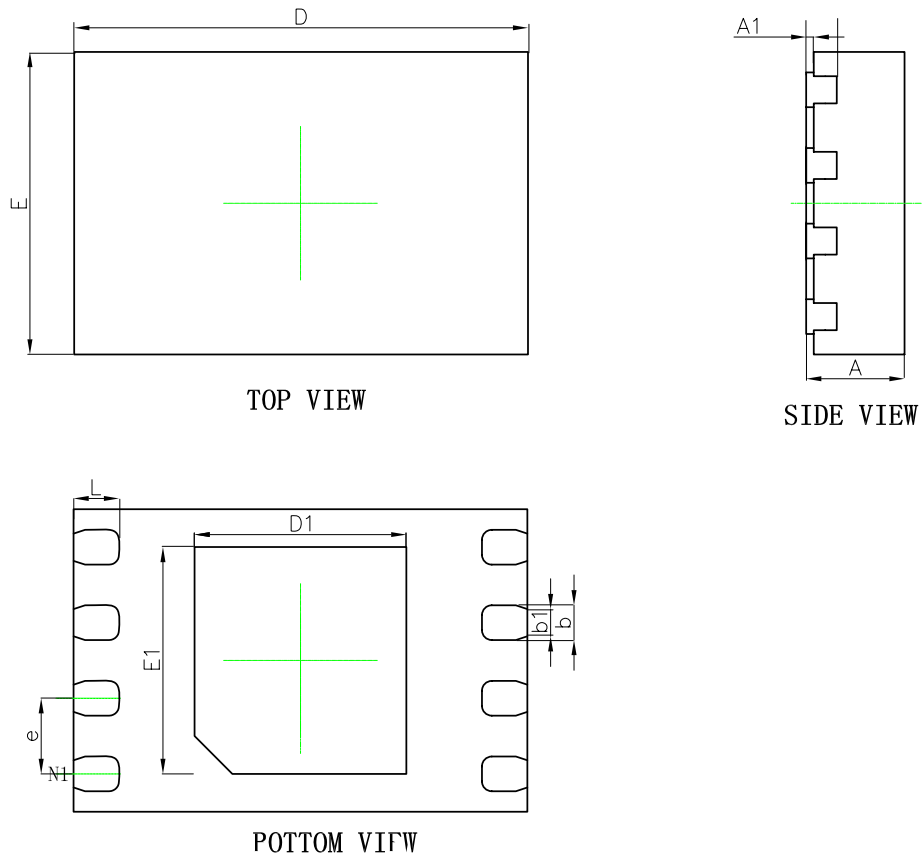
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.850	1.100	0.033	0.043
A1	0.070	0.130	0.003	0.005
A2	0.850	0.900	0.033	0.035
b	0.195	0.245	0.008	0.010
c	0.127 (BSC)		0.005 (BSC)	
D	2.910	3.030	0.115	0.119
E	6.230	6.480	0.245	0.255
E1	4.370	4.430	0.172	0.174
e	0.625	0.675	0.025	0.027
L	0.562	0.638	0.022	0.025
H	0.350 (BSC)		0.014 (BSC)	
α	1°	7°	1°	7°

6.6 SOT23-5 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.030	0.090	0.001	0.004
A2	1.050	1.150	0.041	0.045
b	0.350 (BSC)		0.014 (BSC)	
c	0.152 (BSC)		0.006 (BSC)	
D	2.870	2.970	0.113	0.117
E	2.750	2.850	0.108	0.112
E1	1.550	1.650	0.061	0.065
e1	1.900 (BSC)		0.075 (BSC)	
e2	0.950 (BSC)		0.037 (BSC)	
L	0.350	0.450	0.014	0.018
α	0°	4°	0°	4°

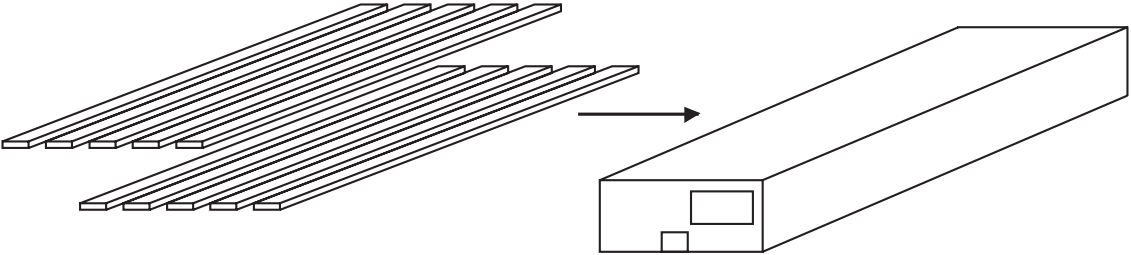
6.7 DFN8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inch	
	Min	Max	Min	Max
A	0.500	0.600	0.020	0.024
A1	-	0.050	-	0.002
A3	0.152(BSC)		0.006(BSC)	
D	2.900	3.100	0.114	0.122
E	1.900	2.100	0.075	0.083
D1	1.300	1.500	0.051	0.059
E1	1.400	1.600	0.055	0.063
b	0.200	0.300	0.008	0.015
b1	0.150(BSC)		0.007(BSC)	
e	0.500(BSC)		0.020(BSC)	
L	0.200	0.400	0.008	0.016

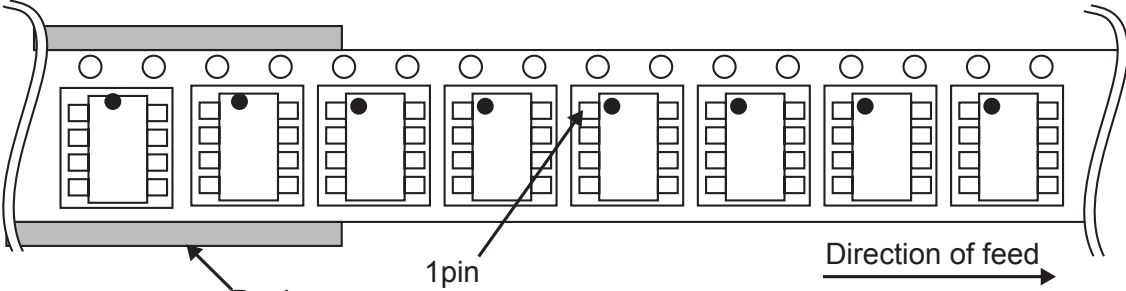
6.8 Tape and Reel Information

Container	Tube
Quantity	2000pcs
Direction of feed	Direction of products is fixed in a container tube



* Order quantity needs to be multiple of the minimum quantity.

Tape	Embossed carrier tape
Quantity	4000pcs (3000pcs for SOT23-5 and DFN8 package)
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



* Order quantity needs to be multiple of the minimum quantity.

7. Notice**•General Precaution**

- 1) Before you use our Products, you are requested to carefully read this document and fully understand its contents. BM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any BM's Products against warning, caution or note contained in this document.
- 2) All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using BM's Products, please confirm the latest information with a BM sales representative.

•Precaution on using BM Products

- 1) Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the BM sales representative in advance. Unless otherwise agreed in writing by BM in advance, BM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any BM's Products for Specific Applications.
- 2) BM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3) Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, BM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any BM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust

[c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂

[d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves

[e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items

[f] Sealing or coating our Products with resin or other coating materials

[g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering

[h] Use of the Products in places subject to dew condensation

4) The Products are not subject to radiation-proof design.

5) Please verify and confirm characteristics of the final or mounted products in using the Products.

6) In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse) is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7) De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8) Confirm that operation temperature is within the specified range described in the product specification.

9) BM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

●Precaution for Mounting / Circuit board design

1) When a highly active halogen us (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2) In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the BM representative in advance. For details, please refer to BM Mounting specification

●Precautions Regarding Application Examples and External Circuits

1) If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2) You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own

independent verification and judgment in the use of such information contained in this document. BM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

●Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

●Precaution for Storage / Transportation

1) Product performance and soldered connections may deteriorate if the Products are stored in the places where:

- [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
- [b] the temperature or humidity exceeds those recommended by BM
- [c] the Products are exposed to direct sunshine or condensation
- [d] the Products are exposed to high Electrostatic

2) Even under BM recommended storage condition, solder ability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solder ability before using Products of which storage time is exceeding the recommended storage time period.

3) Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4) Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

●Precaution for Product Label

QR code printed on BM Products label is for BM's internal use only.

●Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

●Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with BM representative in case of export.

●Precaution Regarding Intellectual Property Rights

- 1) All information and data including but not limited to application example contained in this document is for reference only. BM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. BM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.
- 2) No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of BM or any third parties with respect to the information contained in this document.

●Other Precaution

- 1) The information contained in this document is provided on an “as is” basis and BM does not warrant that all information contained in this document is accurate and/or error-free. BM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.
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- 5) The proper names of companies or products described in this document are trademarks or registered trademarks of BM, its affiliated companies or third parties.

8. Revision History

Version	Publication date	Pages	Revise Description
1.0	Aug.2012	18	Initial Document Release
1.1	Aug.2013	18	Package Type Update
1.2	Sep.2013	22	Update some English words, sentences' descriptions, grammar and formatting
2.0	Jan.2014	24	Package Type Update
2.1	May.2014	24	Package Type Update
2.2	Jul.2014	24	Package Type Update
2.3	May 2015	24	Package Type Update
2.4	Mar 2018	24	Parameters Improved